

Search Notes

Application No.

10/823,326

Examiner

Stephen W. Smoot

Applicant(s)

JENSEN, DAVID G.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
29	25.01	11/12/2004	SWS
29	25.02	11/12/2004	SWS
29	25.03	11/12/2004	SWS
324	765	11/12/2004	SWS
228	42	11/12/2004	SWS
228	232	11/12/2004	SWS
438	15	11/12/2004	SWS
438	612	11/12/2004	SWS

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner
Same as Above		11/12/2004	SWS

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered all references cited in parent application.	11/12/2004	SWS
Key Words: Solder - Reflow, Plating, Apparatus, System; Packaged Component - IC, Die, Dice, Chip;	11/12/2004	SWS
Testing; Encapsulation - Curing; Inventor Search - David G. Jensen.	11/12/2004	SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	11/12/2004	SWS